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METHOD OF FABRICATING SEMICONDUCTOR HAVING THROUGH HOLE

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ABSTRACT OF THE DISCLOSURE

10 The semiconductor device includes a semiconductor
chip, a tape for mounting the semiconductor chip thereto,
an adhesive resin layer interposed between the
semiconductor chip and the tape, and solder balls
15 attached to the tape. The method of fabricating the
semiconductor chip comprises the step of forming at least
one hole in the tape, after fixing the semiconductor chip
to the tape through the adhesive resin layer. Also, the
TAB tape is made of polyimide having high water
permeability.